

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20150123000 Datasheet update for BQ24196 Information Only Datasheet

Date: 1/28/2015 To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN\_ww\_admin\_team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

## 20150123000 Information Only Datasheet Attachments

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

# DEVICE

BQ24196RGET

#### **CUSTOMER PART NUMBER**

null

Technical details of this Product Change follow on the next page(s).

PCN Number:		20150123000					CN Date:	01/28/2015			
Titl	e: Datasheet u	pdate for BQ2	419	06				•			
Customer Contact:		PCN Manager				ity S	Services				
Cha	ange Type:										
	Assembly Site		Design			Wafer Bump Site					
	Assembly Process	5	$\square$	Data Sheet			Wafer Bum	p Material			
	Assembly Materials			Part number chang	je		Wafer Bum	p Process			
	Mechanical Specification			est Site			Wafer Fab S	Site			
Packing/Shipping/La		/Labeling		Test Process			Wafer Fab I				
						Wafer Fab I	Process				
				PCN Details							
	scription of Chan										
Tex	as Instruments Inc	corporated is a	anno	ouncing an informat	tion only	no	tification.				
The	e product datasheet	:(s) is being u	pda	ted as summarize t	below.						
The	following change l	history provid	es f	urther details							
							ti Te	XAS ISTRUMENTS			
ha?	24196						V IN	STRUMENTS			
-		SED DECEMBER 2014		bq24196 SLUSB98A-OCTOBER 2012-REVISED DECEMBER 2014 www.ti.com							
Changes from Original (October 2012) to Revisio											
Cha	anges from Original (Oct		isior	n A				Page			
		ober 2012) to Rev		n A n section, Device Function	al Modes, A	pplic	ation and				
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### The datasheet number will be changing.

Device Family	Change From:	Change To:
BQ24196	SLUSB98	SLUSB98A

# These changes may be reviewed at the datasheet links provided.

http://www.ti.com/sitesearch/docs/universalsearch.tsp?searchTerm=BQ24196#linkId=1&src=top

Reason for Change:					
To more accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
Electrical specification performance changes as indicated above.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
BQ24196RGER	BQ24196RGET				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com